Kazuhiro Nogita

List of Publications by Year
in descending order

218	7,542	43973	69108
papers	citations	48 h-index	77 g-index

225	225	225	3699
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Eutectic modification and microstructure development in Alâ€“Si Alloys. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2005, 413-414, 243-248.	2.6	271
2	Development of high-temperature solders: Review. Microelectronics Reliability, 2012, 52, 1306-1322.	0.9	248
3	Eutectic nucleation and growth in hypoeutectic Al-Si alloys at different strontium levels. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2001, 32, 949-960.	1.1	224
4	Eutectic nucleation in Alâ€“Si alloys. Acta Materialia, 2004, 52, 4273-4280.	3.8	202
5	Modification of Alâ€“Si alloys with Ba, Ca, Y and Yb. Journal of Light Metals, 2001, 1, 229-240.	0.8	200
6	Eutectic Modification of Al-Si Alloys with Rare Earth Metals. Materials Transactions, 2004, 45, 323-326.	0.4	178
7	Nickel-stabilized hexagonal (Cu, Ni)6Sn5 in Snâ€“Cuâ€“Ni lead-free solder alloys. Scripta Materialia, 2008, 59, 191-194.	2.6	173
8	Stabilisation of Cu6Sn5 by Ni in Sn-0.7Cu-0.05Ni lead-free solder alloys. Intermetallics, 2010, 18, 145-149.	1.8	156
9	Understanding the Origin of Li₂MnO₃ Activation in Liâ€Rich Cathode Materials for Lithiumâ€ion Batteries. Advanced Functional Materials, 2015, 25, 7488-7496.	7.8	151
10	Effects of boron on microstructure in cast titanium alloys. Scripta Materialia, 2008, 59, 538-541.	2.6	147
11	Formation and growth of intragranular fission gas bubbles in UO2 fuels with burnup of 6â€“83 GWd/t. Journal of Nuclear Materials, 1993, 206, 22-34.	1.3	133
12	The role of trace element segregation in the eutectic modification of hypoeutectic Alâ€“Si alloys. Journal of Alloys and Compounds, 2010, 489, 415-420.	2.8	132
13	Irradiation-induced recrystallization in high burnup UO2 fuel. Journal of Nuclear Materials, 1995, 226, 302-310.	1.3	127
14	Aluminium phosphide as a eutectic grain nucleus in hypoeutectic Al-Si alloys. Journal of Electron Microscopy, 2004, 53, 361-369.	0.9	120
15	Cracking and phase stability in reaction layers between Sn-Cu-Ni solders and Cu substrates. Jom, 2009, 61, 45-51.	0.9	119
16	The influence of Ni and Zn additions on microstructure and phase transformations in Snâ€“0.7Cu/Cu solder joints. Acta Materialia, 2015, 83, 357-371.	3.8	119
17	Radiation-induced microstructural change in high burnup UO2 fuel pellets. Nuclear Instruments & Methods in Physics Research B, 1994, 91, 301-306.	0.6	112
18	Combining Sr and Na additions in hypoeutectic Alâ€“Si foundry alloys. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2005, 399, 244-253.	2.6	111

#	Article	IF	Citations
19	Microstructural change and its influence on fission gas release in high burnup UO2 fuel. Journal of Nuclear Materials, 1992, 188, 65-72.	1.3	103
20	Determination of strontium segregation in modified hypoeutectic Alâ€“Si alloy by micro X-ray fluorescence analysis. Scripta Materialia, 2006, 55, 787-790.	2.6	98
21	Granular deformation mechanisms in semi-solid alloys. Acta Materialia, 2011, 59, 4933-4943.	3.8	89
22	Electrochemical and Structural Study of Layered P2â€Type Na_{2/3}Ni_{1/3}Mn_{2/3}O₂ as Cathode Material for Sodiumâ€Ion Battery. Chemistry - an Asian Journal, 2015, 10, 661-666.	1.7	88
23	Critical properties of Cu 6 Sn 5 in electronic devices: Recent progress and a review. Current Opinion in Solid State and Materials Science, 2016, 20, 55-76.	5.6	87
24	Crystallography of Zirconium Hydrides in Recrystallized Zircaloy-2 Fuel Cladding by Electron Backscatter Diffraction. Journal of Nuclear Science and Technology, 2004, 41, 731-740.	0.7	81
25	Cu6Sn5 crystal growth mechanisms during solidification of electronic interconnections. Acta Materialia, 2017, 126, 540-551.	3.8	81
26	Mechanisms of eutectic solidification in Alâ€“Si alloys modified with Ba, Ca, Y and Yb. Journal of Light Metals, 2001, 1, 219-228.	0.8	80
27	Ga-Based Alloys in Microelectronic Interconnects: A Review. Materials, 2018, 11, 1384.	1.3	77
28	Eutectic solidification in hypoeutectic Alâ€“Si alloys: electron backscatter diffraction analysis. Materials Characterization, 2001, 46, 305-310.	1.9	76
29	Kinetics of the Î·â€“Î·â€² transformation in Cu6Sn5. Scripta Materialia, 2011, 65, 922-925.	2.6	68
30	High resolution TEM observation and density estimation of Xe bubbles in high burnup UO2 fuels. Nuclear Instruments & Methods in Physics Research B, 1998, 141, 481-486.	0.6	67
31	The Influence of 0â€“0.1 wt.% Ni on the Microstructure and Fluidity Length of Sn-0.7Cu-xNi. Journal of Electronic Materials, 2008, 37, 32-39.	1.0	67
32	Anisotropic mechanical properties of Cu6Sn5 and (Cu,Ni)6Sn5. Materials Letters, 2012, 86, 46-49.	1.3	67
33	Evidence of the hydrogen release mechanism in bulk MgH2. Scientific Reports, 2015, 5, 8450.	1.6	66
34	Effect of Ni on phase stability and thermal expansion of Cu6â^'xNixSn5 (XÂ=Â0, 0.5, 1, 1.5 and 2). Intermetallics, 2012, 26, 78-85.	1.8	65
35	Rim structure formation and high burnup fuel behavior of large-grained UO2 fuels. Journal of Nuclear Materials, 2000, 278, 54-63.	1.3	62
36	Effects of boron on eutectic modification of hypoeutectic Alâ€“Si alloys. Scripta Materialia, 2003, 48, 307-313.	2.6	62

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37	Columnar to equiaxed transition of eutectic in hypoeutectic aluminiumâ€“silicon alloys. Acta Materialia, 2002, 50, 2537-2546.	3.8	61
38	Engineering the Mgâ€“Mg2Ni eutectic transformation to produce improved hydrogen storage alloys. International Journal of Hydrogen Energy, 2009, 34, 7686-7691.	3.8	61
39	Suppression of Cu 6 Sn 5 in TiO 2 reinforced solder joints after multiple reflow cycles. Materials and Design, 2016, 108, 418-428.	3.3	57
40	Anisotropic thermal expansion of Ni 3 Sn 4 , Ag 3 Sn, Cu 3 Sn, Cu 6 Sn 5 and Î²Sn. Intermetallics, 2017, 91, 50-64.	1.8	57
41	In situ investigation of unidirectional solidification in Snâ€“0.7Cu and Snâ€“0.7Cuâ€“0.06Ni. Acta Materialia, 2011, 59, 4043-4054.	3.8	56
42	Growth orientations and mechanical properties of Cu6Sn5 and (Cu,Ni)6Sn5 on poly-crystalline Cu. Journal of Alloys and Compounds, 2012, 536, 38-46.	2.8	56
43	Rapid Cu6Sn5 growth at liquid Sn/solid Cu interfaces. Scripta Materialia, 2015, 100, 17-20.	2.6	56
44	In-situ investigation of the hydrogen release mechanism in bulk Mg2NiH4. Journal of Power Sources, 2017, 341, 130-138.	4.0	55
45	The influence of Ni additions on the relative stability of Î· and Î·â€²â€ˆCu6Sn5. Applied Physics Letters, 2010, 96, .	1.5	54
46	Effects of Ni and TiO2 additions in as-reflowed and annealed Sn0.7Cu solders on Cu substrates. Journal of Materials Processing Technology, 2017, 242, 235-245.	3.1	54
47	Thermal expansion of Cu₆Sn₅ and (Cu,Ni)₆Sn₅. Journal of Materials Research, 2011, 26, 2660-2664.	1.2	52
48	Evaluation of Silicon Twinning in Hypo-Eutectic Al-Si Alloys. Materials Transactions, 2003, 44, 625-628.	0.4	51
49	Effect of Ni on the Formation and Growth of Primary Cu6Sn5 Intermetallics in Sn-0.7Âwt.%Cu Solder Pastes on Cu Substrates During the Soldering Process. Journal of Electronic Materials, 2016, 45, 154-163.	1.0	51
50	A new phase in stoichiometric Cu6Sn5. Acta Materialia, 2012, 60, 6581-6591.	3.8	50
51	The Effect of Aluminium Content on the Mechanical Properties and Microstructure of Die Cast Binary Magnesium-Aluminium Alloys. Materials Transactions, 2006, 47, 977-982.	0.4	49
52	Kinetics of the polymorphic phase transformation of Cu6Sn5. Acta Materialia, 2014, 69, 135-148.	3.8	48
53	The influence of solder composition on the impact strength of lead-free solder ball grid array joints. Microelectronics Reliability, 2011, 51, 657-667.	0.9	47
54	Intermetallic Formation and Fluidity in Sn-Rich Sn-Cu-Ni Alloys. Journal of Electronic Materials, 2010, 39, 56-69.	1.0	46

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55	A real-time synchrotron X-ray study of primary phase nucleation and formation in hypoeutectic Alâ€“Si alloys. Journal of Crystal Growth, 2015, 430, 122-137.	0.7	45
56	High resolution TEM of high burnup UO2 fuel. Journal of Nuclear Materials, 1997, 250, 244-249.	1.3	44
57	Microstructure Control in Sn–0.7 mass%Cu Alloys. Materials Transactions, 2005, 46, 2419-2425.	0.4	43
58	Development of a microwave sintered TiO2 reinforced Snâ€“0.7wt%Cuâ€“0.05wt%Ni alloy. Materials and Design, 2015, 82, 136-147.	3.3	43
59	In situ imaging of microstructure formation in electronic interconnections. Scientific Reports, 2017, 7, 40010.	1.6	43
60	Eutectic Growth Mode in Strontium, Antimony and Phosphorus Modified Hypoeutectic Al-Si Foundry Alloys. Materials Transactions, 2001, 42, 393-396.	0.4	42
61	Phase stability and thermal expansion behavior of Cu6Sn5 intermetallics doped with Zn, Au and In. Intermetallics, 2013, 43, 85-98.	1.8	41
62	Porosity formation in aluminium alloy A356 modified with Ba, Ca, Y and Yb. Journal of Light Metals, 2001, 1, 241-249.	0.8	39
63	The Maximum Fluidity Length of Solidifying Sn-Cu-Ag-Ni Solder Alloys. Journal of Electronic Materials, 2008, 37, 51-60.	1.0	39
64	Inhibiting Cracking of Interfacial Cu6Sn5 by Ni Additions to Sn-based Lead-free Solders. Transactions of the Japan Institute of Electronics Packaging, 2009, 2, 46-54.	0.3	39
65	Nanoindentation characterization of intermetallic compounds formed between Snâ€“Cu (â€“Ni) ball grid arrays and Cu substrates. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2009, 164, 44-50.	1.7	38
66	Eutectic solidification and its role in casting porosity formation. Jom, 2004, 56, 52-58.	0.9	37
67	The influence of ageing on the stabilisation of interfacial (Cu,Ni)6(Sn,Zn)5 and (Cu,Au,Ni)6Sn5 intermetallics in Pb-free Ball Grid Array (BGA) solder joints. Journal of Alloys and Compounds, 2016, 685, 471-482.	2.8	37
68	Characterising the polymorphic phase transformation at a localised point on a Cu6Sn5 grain. Materials Characterization, 2018, 138, 113-119.	1.9	37
69	Investigating the mechanical properties, creep and crack pattern of Cu6Sn5 and (Cu,Ni)6Sn5 on diverse crystal planes. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2013, 566, 126-133.	2.6	35
70	The effect of Bi on the microstructure, electrical, wettability and mechanical properties of Sn-0.7Cu-0.05Ni alloys for high strength soldering. Materials and Design, 2020, 186, 108281.	3.3	35
71	Real time synchrotron X-ray observations of solidification in hypoeutectic Alâ€“Si alloys. Materials Characterization, 2013, 85, 134-140.	1.9	34
72	Characterisation of lithium-ion battery anodes fabricated via in-situ Cu6Sn5 growth on a copper current collector. Journal of Power Sources, 2019, 415, 50-61.	4.0	34

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73	Shear and tensile impact strength of lead-free solder ball grid arrays placed on Ni (P)/Au surface-finished substrates. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2010, 171, 162-171.	1.7	33
74	Eutectic Solidification Mode in Sodium Modified Al-7 mass%Si-3.5 mass%Cu-0.2 mass%Mg Casting Alloys. Materials Transactions, 2001, 42, 1981-1986.	0.4	30
75	Effects of Boron-strontium Interactions on Eutectic Modification in Al-10 mass%Si Alloys. Materials Transactions, 2003, 44, 692-695.	0.4	30
76	Determination of Eutectic Solidification Mode in Sr-modified Hypoeutectic Al-Si Alloys by EBSD. Materials Transactions, 2001, 42, 207-214.	0.4	29
77	Solidification mechanisms of unmodified and strontium-modified hypereutectic aluminiumâ€“silicon alloys. Philosophical Magazine, 2004, 84, 1683-1696.	0.7	29
78	Eutectic grain size and strontium concentration in hypoeutectic aluminiumâ€“silicon alloys. Journal of Alloys and Compounds, 2006, 422, 184-191.	2.8	29
79	Influence of Composition on the Morphology of Primary Cu6Sn5 in Sn-4Cu Alloys. Journal of Electronic Materials, 2013, 42, 256-262.	1.0	29
80	Properties of CuGa2 Formed Between Liquid Ga and Cu Substrates at Room Temperature. Journal of Electronic Materials, 2020, 49, 128-139.	1.0	29
81	Formation of Pellet-Cladding Bonding Layer in High Burnup BWR Fuels. Journal of Nuclear Science and Technology, 1997, 34, 679-686.	0.7	28
82	Creep and Mechanical Properties of Cu6Sn5 and (Cu,Ni)6Sn5 at Elevated Temperatures. Journal of Electronic Materials, 2013, 42, 304-311.	1.0	28
83	Effect of grain size on recrystallization in high burnup fuel pellets. Journal of Nuclear Materials, 1997, 248, 196-203.	1.3	27
84	Epitaxial growth of Cu6Sn5 formed at Sn-based lead-free solder/non-textured polycrystalline Cu plate interface. Materials Letters, 2009, 63, 2687-2690.	1.3	27
85	Non-Metal Reinforced Lead-Free Composite Solder Fabrication Methods and its Reinforcing Effects to the Suppression of Intermetallic Formation: Short Review. Applied Mechanics and Materials, 0, 421, 260-266.	0.2	27
86	XRD study of the kinetics of Î²â€‰â†”â€‰Îµ transformations in tin. Philosophical Magazine, 2013, 93, 3627-3647.	0.7	27
87	Influence of Ni on the refinement and twinning of primary Cu6Sn5 in Sn-0.7Cu-0.05Ni. Intermetallics, 2018, 102, 34-45.	1.8	27
88	Thermal conductivities of irradiated UO2 and (U,Gd)O2. Journal of Nuclear Materials, 2001, 288, 57-65.	1.3	26
89	Determination of the minimum Ni concentration to prevent the Î· to Î·4+1 polymorphic transformation of stoichiometric Cu6Sn5. Scripta Materialia, 2013, 68, 595-598.	2.6	26
90	Rim structure formation of isothermally irradiated UO2 fuel discs. Journal of Nuclear Materials, 2001, 288, 20-28.	1.3	25

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91	The effects of precipitation strengthening and solid solution strengthening on strain rate sensitivity of lead-free solders: Review. Microelectronics Reliability, 2018, 84, 170-180.	0.9	25
92	Microstructure and mechanical properties of high pressure die cast magnesium alloy AE42 with 1% strontium. International Journal of Cast Metals Research, 2004, 17, 170-173.	0.5	24
93	Effects of Phosphorus on Microstructure and Fluidity of Sn-0.7Cu-0.05Ni Lead-Free Solder. Materials Transactions, 2008, 49, 443-448.	0.4	24
94	Ni segregation in the interfacial (Cu,Ni)6Sn5 intermetallic layer of Sn-0.7Cu-0.05Ni/Cu ball grid array (BGA) joints. Intermetallics, 2014, 54, 20-27.	1.8	24
95	The influence of topological structure on bulk glass formation in Al-based metallic glasses. Scripta Materialia, 2011, 65, 755-758.	2.6	23
96	Solidification of Sn-0.7Cu-0.15Zn Solder: In Situ Observation. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2014, 45, 918-926.	1.1	23
97	In-situ synchrotron X-ray diffraction investigation of the hydriding and dehydriding properties of a cast Mgâ€“Ni alloy. Journal of Alloys and Compounds, 2015, 636, 249-256.	2.8	23
98	In Situ TEM Observations of Cu6Sn5 Polymorphic Transformations in Reaction Layers Between Sn-0.7Cu Solders and Cu Substrates. Jom, 2016, 68, 2871-2878.	0.9	23
99	The Effect of Ni and Bi Additions on the Solderability of Sn-0.7Cu Solder Coatings. Journal of Electronic Materials, 2020, 49, 1-12.	1.0	23
100	Crystallography of Zirconium Hydrides in Recrystallized Zircaloy-2 Fuel Cladding by Electron Backscatter Diffraction. , 0, .		23
101	Atom locations in a Ni doped Î·-(Cu,Ni)6Sn5 intermetallic compound. Scripta Materialia, 2019, 158, 1-5.	2.6	22
102	A rheological assessment of the effect of trace level Ni additions on the solidification of Snâ€“0.7Cu. Scripta Materialia, 2006, 54, 1557-1562.	2.6	21
103	Effect of Zn, Au, and In on the polymorphic phase transformation in Cu₆Sn₅intermetallics. Journal of Materials Research, 2012, 27, 2609-2614.	1.2	21
104	Grain Size Measurements in Mg-Al High Pressure Die Castings Using Electron Back-Scattered Diffraction (EBSD). Materials Transactions, 2004, 45, 3114-3119.	0.4	20
105	Influence of calcium on the microstructure and properties of an Al-7Si-0.3Mg-xFe alloy. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2006, 37, 2581-2587.	1.1	20
106	Al8Mn5 Particle Settling and Interactions with Oxide Films in Liquid AZ91 Magnesium Alloys. Jom, 2019, 71, 2235-2244.	0.9	20
107	Thermal Recovery of Radiation Defects and Microstructural Change in Irradiated UO2 Fuels.. Journal of Nuclear Science and Technology, 1993, 30, 900-910.	0.7	20
108	Suppression of Cu3Sn in the Sn-10Cu peritectic alloy by the addition of Ni. Journal of Alloys and Compounds, 2018, 766, 1003-1013.	2.8	19

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109	Interfacial Reactions between Ga and Cu-10Ni Substrate at Low Temperature. ACS Applied Materials & Interfaces, 2020, 12, 21045-21056.	4.0	19
110	Thermal Recovery of Radiation Defects and Microstructural Change in Irradiated UO₂Fuels. Journal of Nuclear Science and Technology, 1993, 30, 900-910.	0.7	18
111	Effect of trace Na additions on the hydrogen absorption kinetics of Mg₂Ni. Journal of Materials Research, 2016, 31, 1316-1327.	1.2	17
112	Intermetallic formation mechanisms and properties in room-temperature Ga soldering. Journal of Alloys and Compounds, 2020, 826, 154221.	2.8	17
113	Real-time synchrotron x-ray observations of equiaxed solidification of aluminium alloys and implications for modelling. IOP Conference Series: Materials Science and Engineering, 2015, 84, 012014.	0.3	16
114	In situ studies revealing dendrite and eutectic growth during the solidification of Sn-0.7Cu-0.5Ag Pb-free solder alloy. Journal of Alloys and Compounds, 2019, 797, 804-810.	2.8	16
115	Re-evaluation of the mechanical properties and creep resistance of commercial magnesium die-casting alloy AE44. Journal of Magnesium and Alloys, 2021, 9, 1537-1545.	5.5	16
116	Depth profiles of damage accumulation in UO2 and (U,Gd)O2 pellets irradiated with 100 MeV iodine ions. Journal of Nuclear Materials, 1999, 273, 302-309.	1.3	15
117	Imaging the Polymorphic Transformation in a Single Cu6Sn5 Grain in a Solder Joint. Materials, 2018, 11, 2229.	1.3	15
118	Synchrotron Micro-XRF Measurements of Trace Element Distributions in BGA Type Solders and Solder Joints. Transactions of the Japan Institute of Electronics Packaging, 2010, 3, 40-46.	0.3	14
119	Relationship between free solder thickness to the solderability of Snâ€“0.7Cuâ€“0.05Ni solder coating during soldering. Journal of Materials Science: Materials in Electronics, 2019, 30, 3669-3677.	1.1	14
120	Evidence of Copper Separation in Lithiated Cu₆Sn₅ Lithium-Ion Battery Anodes. ACS Applied Energy Materials, 2020, 3, 141-145.	2.5	14
121	Systematic investigation of the effect of Ni concentration in Cu-xNi/Sn couples for high temperature soldering. Acta Materialia, 2022, 226, 117661.	3.8	14
122	TEM analysis of pellet-cladding bonding layer in high burnup BWR fuel. Nuclear Instruments & Methods in Physics Research B, 1996, 116, 521-526.	0.6	13
123	Formation and Mechanical Properties of Intermetallic Compounds in Sn-Cu High-Temperature Lead-Free Solder Joints. Materials Science Forum, 2010, 654-656, 2450-2454.	0.3	13
124	Peritectic phase formation kinetics of directionally solidifying Sn-Cu alloys within a broad growth rate regime. Acta Materialia, 2021, 220, 117295.	3.8	13
125	Effects of element addition on the Î²â†'Î± transformation in tin. Philosophical Magazine Letters, 2014, 94, 53-62.	0.5	12
126	Kinetics of the Î² â†' Î± Transformation of Tin: Role of Î±-Tin Nucleation. Crystal Growth and Design, 2015, 15, 5767-5773.	1.4	12

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127	Influence of Bi Addition on Wettability and Mechanical Properties of Sn-0.7Cu Solder Alloy. Solid State Phenomena, 2018, 273, 27-33.	0.3	12
128	The effects of Ni on inhibiting the separation of Cu during the lithiation of Cu6Sn5 lithium-ion battery anodes. Journal of Power Sources, 2019, 440, 227085.	4.0	12
129	Experimental Determination of the Sn-Cu-Ni Phase Diagram for Pb-Free Solder Applications. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2019, 50, 502-516.	1.0	12
130	XPS Analysis of Oxide Films on Lead-Free Solders with Trace Additions of Germanium and Gallium. Materials Science Forum, 0, 857, 63-67.	0.3	10
131	Effect of trace Na additions on the hydriding kinetics of hypo-eutectic Mgâ€“Ni alloys. International Journal of Hydrogen Energy, 2017, 42, 6851-6861.	3.8	10
132	Effects of Ni and Cu Antisite Substitution on the Phase Stability of CuGa2 from Liquid Ga/Cuâ€“Ni Interfacial Reaction. ACS Applied Materials & Interfaces, 2019, 11, 32523-32532.	4.0	10
133	The effect of Na addition on the first hydrogen absorption kinetics of cast hypoeutectic Mgâ€“La alloys. International Journal of Hydrogen Energy, 2021, 46, 27096-27106.	3.8	10
134	Effect of Grain Size on Microstructural Change and Damage Recovery in UO2 Fuels Irradiated to 23 GWd/t.. Journal of Nuclear Science and Technology, 1994, 31, 929-936.	0.7	10
135	Na-modified cast hypo-eutectic Mgâ€“Mg2Si alloys for solid-state hydrogen storage. Journal of Power Sources, 2022, 538, 231538.	4.0	10
136	Effect of Grain Size on Microstructural Change and Damage Recovery in UO₂Fuels Irradiated to 23 GWd/t. Journal of Nuclear Science and Technology, 1994, 31, 929-936.	0.7	9
137	Metallic tin recovery from wave solder dross. International Journal of Mineral Processing, 2015, 137, 98-105.	2.6	9
138	Origin of Primary Cu6Sn5 in Hypoeutectic Solder Alloys and a Method of Suppression to Improve Mechanical Properties. Journal of Electronic Materials, 2021, 50, 710-722.	1.0	9
139	Rapid fabrication of tin-copper anodes for lithium-ion battery applications. Journal of Alloys and Compounds, 2021, 867, 159031.	2.8	9
140	Tin pest in lead-free solders? Fundamental studies on the effect of impurities on phase transformation kinetics. , 2014, , .		8
141	Comparison of solidification behavior between in situ observation and simulation of Feâ€“Câ€“Si system. Journal of Alloys and Compounds, 2014, 613, 132-138.	2.8	8
142	Direct observation of the Ni stabilising effect in interfacial (Cu,Ni)6Sn5 intermetallic compounds. Materialia, 2020, 9, 100530.	1.3	8
143	Microstructure, thermal behavior and joint strength of Sn-0.7Cu-1.5Bi/electroless nickel immersion gold (ENIG). Journal of Materials Research and Technology, 2021, 12, 1700-1714.	2.6	8
144	The Effects of Temperature and Solute Diffusion on Volume Change in Sn-Bi Solder Alloys. Jom, 2022, 74, 1739-1750.	0.9	8

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145	Hydrogen desorption of Mgâ€“Mg2Ni hypo-eutectic alloys in air, Ar, CO2, N2 and H2. Journal of Alloys and Compounds, 2013, 580, S140-S143.	2.8	7
146	Effects of Bi in Sn-Cu based lead-free solder alloys and interconnects. , 2017, , .		7
147	Solidification path and microstructure evolution of Mg-3Al-14La alloy: Implications for the Mg-rich corner of the Mg-Al-La phase diagram. Journal of Alloys and Compounds, 2019, 784, 527-534.	2.8	7
148	Microstructure and growth kinetic study in Snâ€“Cu transient liquid phase sintering solder paste. Journal of Materials Science: Materials in Electronics, 2020, 31, 11077-11094.	1.1	7
149	Effects of Surface Finish on Sn-3.0Ag-0.5Cu Solder Joint Microstructure and Strength. Journal of Electronic Materials, 2021, 50, 855-868.	1.0	7
150	Atomic locations of minor dopants and their roles in the stabilization of<mml:math xmlns:mml="http://www.w3.org/1998/Math/MathML"><mml:mrow><mml:mi>Î·</mml:mi><mml:mtext>â€²</mml:mtext><mml:mi mathvariant="normal">C</mml:mi><mml:msub><mml:mi mathvariant="normal">u</mml:mi><mml:mn>6</mml:mn></mml:msub><mml:mi mathvariant="normal">S</mml:mi><mml:msub><mml:mi mathvariant="normal">n</mml:mi><mml:mn>5</mml:mn></mml:msub></mml:mrow></mml:math>. Physi	0.9	7
151	The effect of Ni on the growth morphology of primary Î²-phase in an In-35Âwt%Sn alloy. Journal of Alloys and Compounds, 2022, 897, 163172.	2.8	7
152	Hydrogen sorption behaviour of Mg-5wt.%La alloys after the initial hydrogen absorption process. International Journal of Hydrogen Energy, 2022, 47, 16132-16143.	3.8	7
153	Corrosion behavior of unirradiated oxide fuel pellets in high temperature water. Journal of Nuclear Materials, 1995, 227, 32-39.	1.3	6
154	Real Time Synchrotron X-Ray Imaging for Nucleation and Growth of Cu₆Sn₅ in Sn-7Cu-0.05Ni High Temperature Lead-Free Solder Alloys. Advanced Materials Research, 2012, 626, 200-204.	0.3	6
155	The Interaction of Sn-Ga Alloys and Au Coated Cu Substrates. Solid State Phenomena, 0, 273, 3-8.	0.3	6
156	Interfacial reactions between Ga and Cu-xNi (x=0, 2, 6, 10, 14) substrates and the strength of Cu-xNi/Ga/Cu-xNi joints. Intermetallics, 2021, 133, 107168.	1.8	6
157	Properties of Sn-3Âwt%Ag-5Âwt%Cu alloys with Cu6Sn5 intermetallics grain refined by Mg. Materials Today Communications, 2022, 31, 103221.	0.9	6
158	The Performance of Lead-Free Solders During a Long-Distance Electric Vehicle Race. Transactions of the Japan Institute of Electronics Packaging, 2010, 3, 104-109.	0.3	5
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